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Electronic Patent Application Submission
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EFS ID: 60530
Application ID: 10626150
Title of Invention: PLASTIC INTEGRATED CIRCUIT
PACKAGE AND METHOD AND
LEADFRAME FOR MAKING THE
PACKAGE
First Named Inventor: THOMAS GLENN
Domestic/Foreign Application: Domestic Application
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**TRANSMITTAL**

Electronic Version v1.1

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Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE									
Application Number: 10/626150 Date: 2003-07-24 First Named Applicant: THOMAS P. Confirmation Number: 9302 Attorney Docket Number: AMKOR007C2										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
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Documents being submitted	Files									
us-ids	ids6-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of Invention

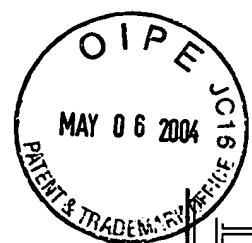
PLASTIC INTEGRATED CIRCUIT PACKAGE AND
AND LEADFRAME FOR MAKING THE PACKAGE

Application Number: 10/626150
Confirmation Number: 9302
First Named Applicant: THOMAS GLENN
Attorney Docket Number: AMKOR007C2
Art Unit: 2815
Search string: (6348726 or 6355502 or 6369447 or 6369454 or
6373127 or 6380048 or 6384472 or 6388336 or
6395578 or 6410979 or 6400004 or 6414385 or
6420779 or 6429508 or 6437429 or 6444499 or
6448633 or 6452279 or 6459148 or 6464121 or
6476469 or 6476474 or 6482680 or 6498099 or
6498392 or 6507096 or 6507120 or 6534849 or
6545332 or 6545345 or 6559525 or 6566168 or
6583503 or 6667546).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	2	6355502	2002-03-12	Kang et al.			
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	34	6667546	2003-12-23	Huang et al.

Signature

Examiner Name	Date